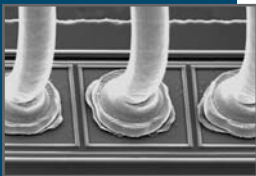
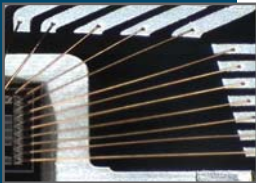
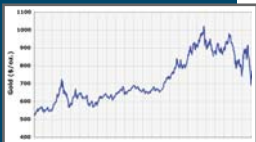
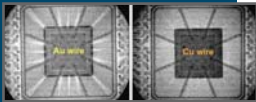
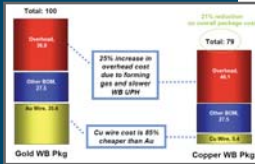


Advanced Packaging Update: Market and Technology Trends

Vol. 2, 2008



The second volume of the Advanced Packaging Update for 2008 provides an updated economic outlook for the next four quarters. This issue features TechSearch International's annual survey on IC package assembly price trends. Packages include QFPs, PBGAs, flip chip PBGAs, QFNs, and laminate CSPs. An analysis of the trends in the movement to copper wire bonding as a cost-savings strategy is also provided. Special coverage of substrate design rules from suppliers of organic flip chip substrates, PBGAs, and laminate CSPs worldwide is provided. The design rules include body size, core thickness, via and pad diameter, minimum bump pitch supported, and substrate finish.

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ASE Materials, Daisho Denshi, Eastern, Endicott Interconnect Technologies, Fujitsu Interconnect Technologies, Ibiden, JCI, Kinsus, Kyocera SLC Technologies, Microcircuit Technology, Mitsui Chemicals, Nan Ya PCB Corporation, NEC Toppan Circuit Solutions, NTK Technologies, PPT, Samsung Electro-Mechanics, Samsung Techwin, Shinko Electric, Simmtech, Sumitomo Metal Mining-Shinko, Tripod Technology, Unimicron

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Annual subscription – \$3,200 (4 issues)
Single issue – \$950


TechSearch
INTERNATIONAL

4801 Spicewood Springs Road • Suite 150
Austin, Texas 78759
Tel: 512-372-8887 • Fax: 512-372-8889
tsi@techsearchinc.com • www.techsearchinc.com